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1. (Amended) A semiconductor laser apparatus comprising a semiconductor laser chip whose bottom is die-bonded to a bonding surface with a conductive die-bonding paste, said semiconductor laser chip having a light-emitting point at each of opposed end surfaces thereof,

Sub B1
wherein the conductive die-bonding paste adheres to a lower part of each end surface of the chip, and a highest position of the conductive die-bonding paste on said lower part of each end surface of the semiconductor laser chip is at a height of more than 0.01 mm from the bonding surface and hence from the bottom of the semiconductor laser chip, but is below the light-emitting point of the semiconductor laser chip.

Please add the following new claims:

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10. (New) The apparatus of claim 1, wherein the apparatus is provided in an optical pick-up using a three-beam scheme.

11. (New) The apparatus of claim 1, wherein the highest position of the conductive die-bonding paste on said lower part of each end surface is within 0.04 mm of the light-emitting point.

12. (New) The apparatus of claim 1, wherein the conductive die-bonding paste comprises epoxy resin and at least 80% by weight conductive filler of metal particles of flakes.

Sub (2)
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13. (New) A semiconductor laser apparatus comprising:

a semiconductor laser chip die-bonded to a bonding surface with a conductive die-bonding paste, said semiconductor laser chip having a light-emitting point at at least one end surface thereof,

wherein a highest position at which the conductive die-bonding paste adheres to at least one end surface of the semiconductor laser chip is at a height of more than 0.01 mm from the bonding surface, but is below the light-emitting point of the semiconductor laser chip; and

wherein the conductive die-bonding paste comprises epoxy resin and at least 80% by weight conductive filler of metal particles or flakes.

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14. (New) A semiconductor laser apparatus for use in an optical pickup using a three-beam scheme for optical disks, the semiconductor laser apparatus comprising a semiconductor laser chip whose bottom is die-bonded to a bonding surface with a conductive die-bonding paste, said semiconductor laser chip including a light-emitting point at each of opposed end surfaces thereof,

where the conductive die-bonding paste adheres to a lower part of each end surface of the chip from the bottom up to a height below the light emitting point so that